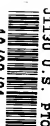


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Docket No.: AB-1169 US

Box Patent Application  
Commissioner For Patents  
Washington, D. C. 20231

December 20, 2001

Enclosed herewith for filing is a patent application, as follows:

Inventor(s): Cheol Joon Yoo  
 Title: Cleaner For Molding Apparatus Of Semiconductor Chip Packages

☒ Return Receipt Postcard  
☒ This Transmittal Letter (in duplicate)  
☐ page(s) Specification (not including claims)  
☐ page(s) Claims  
☐ page Abstract  
☐ Sheet(s) of Drawings  
☐ page(s) Declaration For Patent Application and Power of Attorney  
☐ page(s) Recordation Form Cover Sheet (in duplicate)  
☐ page(s) Assignment  
☒ Other: Certified copy of Korean Patent Application No. 2001-25410

**CLAIMS AS FILED**

For	Number <u>Filed</u>		Number <u>Extra</u>		Rate		\$	Basic Fee <u>740.00</u>
Total Claims	20	-20 =	0	x	\$18.00	=	\$	0.00
Independent Claims	3	-3 =	0	x	\$84.00	=	\$	0.00

Please make the following charges to Deposit Account 19-2386:

- ☒ Total fee for filing the patent application in the amount of \$ 740.00  
☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account 19-2386.

**EXPRESS MAIL LABEL NO:**

EL 884 817 420 US

December 20, 2001

Respectfully submitted,

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